

Title (en)

PLANARIZATION PROCESS TO ACHIEVE IMPROVED UNIFORMITY ACROSS SEMICONDUCTOR WAFERS

Title (de)

PLANARISIERUNGSVERFAHREN ZUR VERBESSERUNG DER GLEICHFÖRMIGKEIT VON HALBLEITERSCHEIBEN

Title (fr)

PROCEDE DE PLANARISATION PERMETTANT D'OBTENIR UNE UNIFORMITE AMELIOREE SUR DES PLAQUETTES DE SEMI-CONDUCTEURS

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Application

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- US 49254100 A 20000127

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Citation (search report)

See references of WO 0156070A1

Citation (examination)

- US 5923993 A 19990713 - SAHOTA KASHMIR S [US]
- WO 9719467 A1 19970529 - FRANCE TELECOM [FR], et al
- US 5952241 A 19990914 - BAKER DANIEL CLAIRE [US], et al

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